



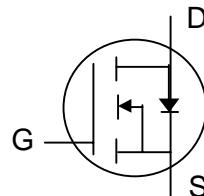
N-channel Enhancement-mode Power MOSFET

Simple Drive Requirement

Small Package Outline

Low Gate Charge

RoHS-compliant, Halogen-free



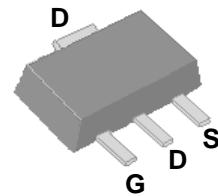
BV_{DSS}	60V
$R_{DS(ON)}$	90mΩ
I_D	2.7A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

The AP2310GG-HF-3 is in the popular SOT-89 small surface-mount package which is widely used in commercial and industrial applications where a small board footprint is required.

This device is well suited for use in medium current applications such as load switches.



SOT-89 (G)

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	60	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D at $T_A = 25^\circ\text{C}$	Continuous Drain Current ³	2.7	A
I_D at $T_A = 70^\circ\text{C}$	Continuous Drain Current ³	2.2	A
I_{DM}	Pulsed Drain Current ¹	10	A
P_D at $T_A = 25^\circ\text{C}$	Total Power Dissipation	1.25	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	100	°C/W

Ordering Information

AP2310GG-HF-3TR : in RoHS-compliant, halogen-free SOT-89, shipped on tape and reel, 1000pcs/reel



Electrical Specifications at $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=250\text{uA}$	60	-	-	V
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=10\text{V}$, $\text{I}_D=2.5\text{A}$	-	-	90	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=4.5\text{V}$, $\text{I}_D=1.5\text{A}$	-	-	120	$\text{m}\Omega$
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$, $\text{I}_D=250\text{uA}$	1	-	3	V
g_{fs}	Forward Transconductance ²	$\text{V}_{\text{DS}}=10\text{V}$, $\text{I}_D=2.5\text{A}$	-	7	-	S
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=48\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$	-	-	10	uA
I_{GSS}	Gate-Source Leakage	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Q_{g}	Total Gate Charge ²	$\text{I}_D=2.5\text{A}$	-	6.5	10.5	nC
Q_{gs}	Gate-Source Charge		-	1.5	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$\text{V}_{\text{GS}}=4.5\text{V}$	-	3.5	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time ²	$\text{V}_{\text{DS}}=30\text{V}$	-	5	-	ns
t_{r}	Rise Time	$\text{I}_D=1\text{A}$	-	5	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	17	-	ns
t_{f}	Fall Time	$\text{V}_{\text{GS}}=10\text{V}$	-	4	-	ns
C_{iss}	Input Capacitance	$\text{V}_{\text{GS}}=0\text{V}$	-	550	880	pF
C_{oss}	Output Capacitance	$\text{V}_{\text{DS}}=15\text{V}$	-	70	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	50	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$\text{I}_S=1\text{A}$, $\text{V}_{\text{GS}}=0\text{V}$	-	-	1.3	V
t_{rr}	Reverse Recovery Time ²	$\text{I}_S=2\text{A}$, $\text{V}_{\text{GS}}=0\text{V}$, $d\text{I}/dt=100\text{A}/\mu\text{s}$	-	23	-	ns
			-	23	-	nC

Notes:

1. Pulse width limited by maximum junction temperature.
2. Pulse test - pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
3. Surface mounted on 1 in² copper pad of FR4 board, t $\leq 10\text{sec}$

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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Typical Electrical Characteristics

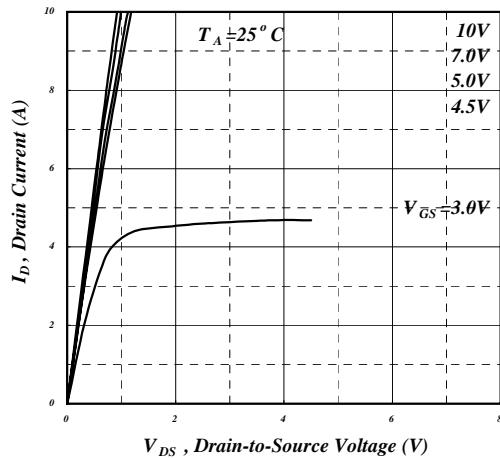


Fig 1. Typical Output Characteristics

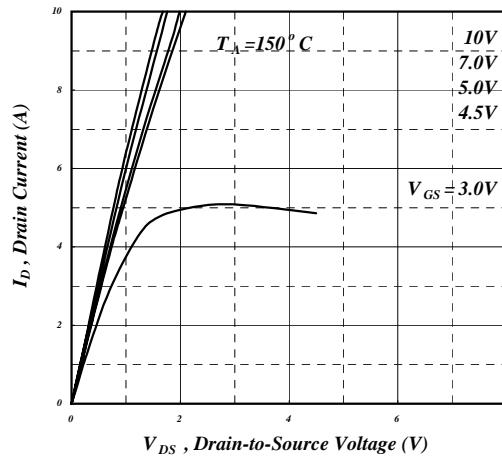


Fig 2. Typical Output Characteristics

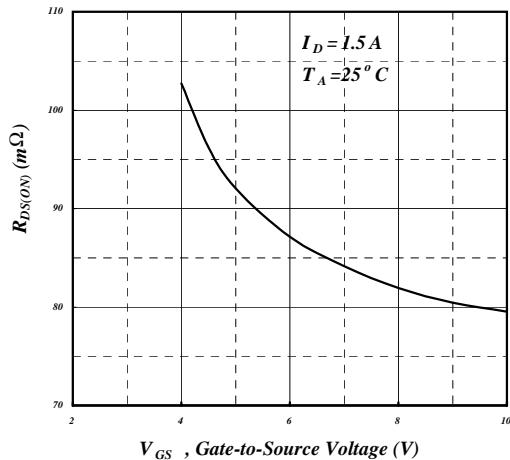


Fig 3. On-Resistance vs.
Gate Voltage

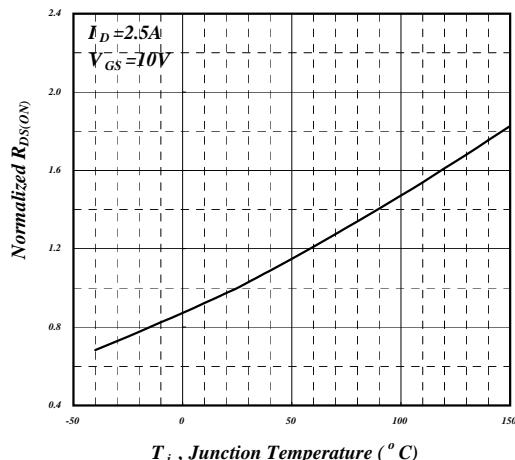


Fig 4. Normalized On-Resistance
vs. Junction Temperature

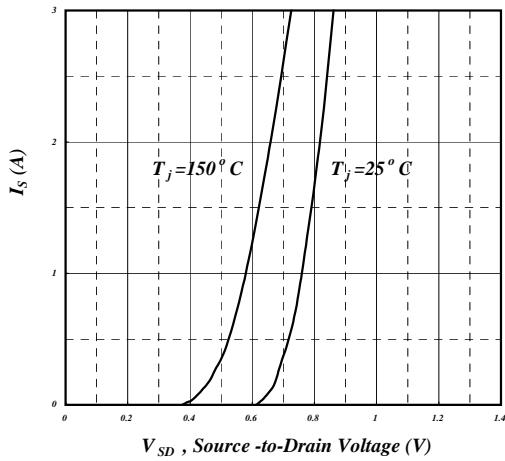


Fig 5. Forward Characteristic of
Reverse Diode

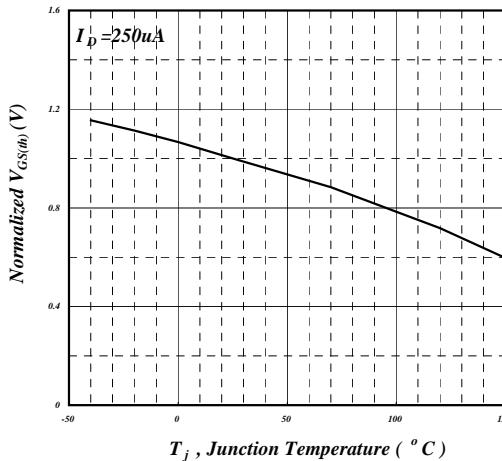


Fig 6. Gate Threshold Voltage vs.
Junction Temperature



Typical Electrical Characteristics (cont.)

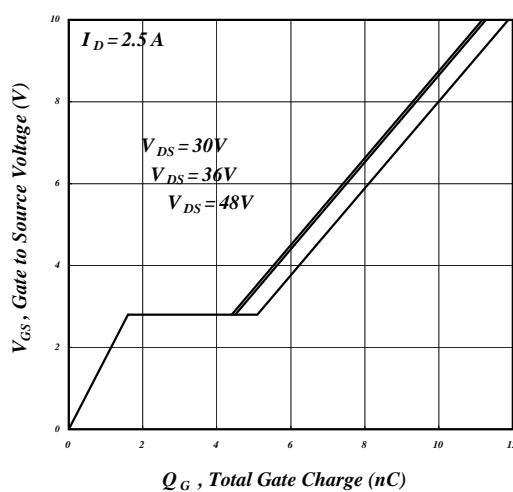


Fig 7. Gate Charge Characteristics

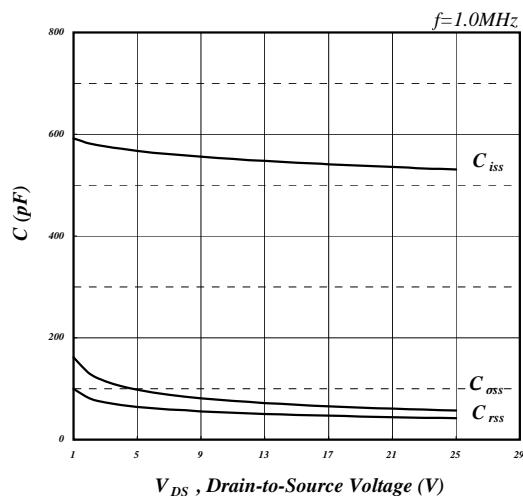


Fig 8. Typical Capacitance Characteristics

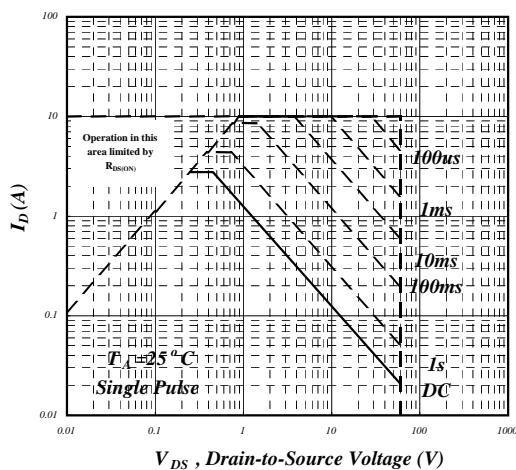


Fig 9. Maximum Safe Operating Area

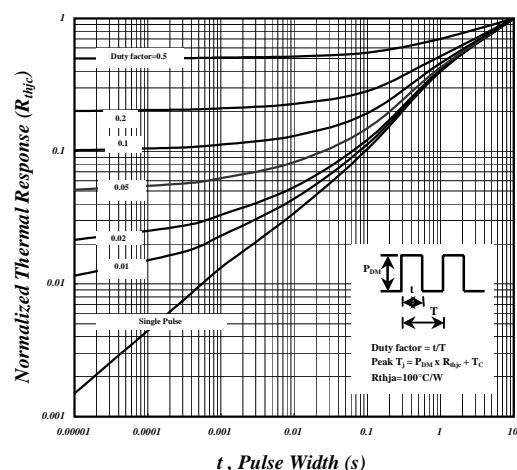


Fig 10. Effective Transient Thermal Impedance

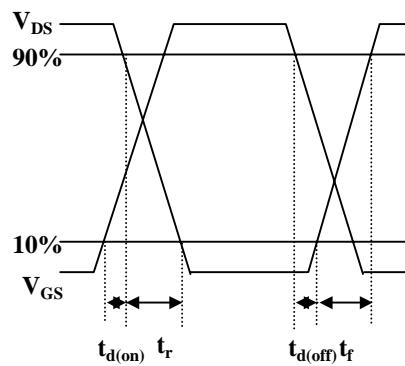


Fig 11. Switching Time Waveform

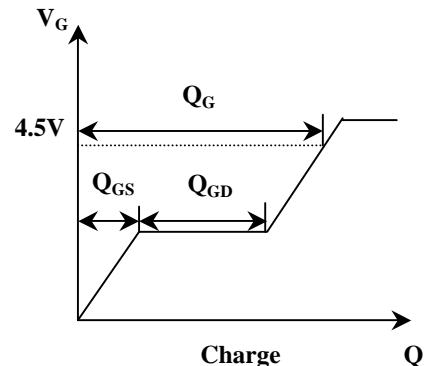
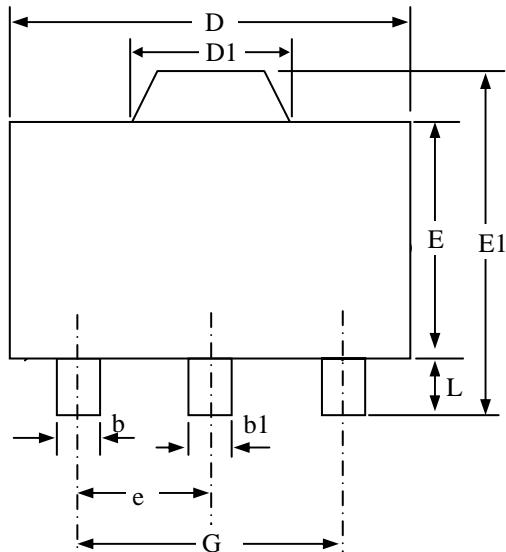


Fig 12. Gate Charge Waveform



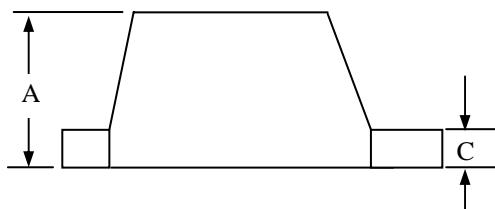
Package Dimensions: SOT-89



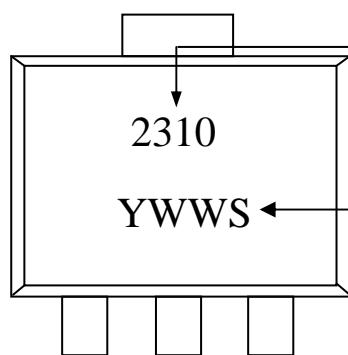
SYMBOLS	Millimeters		
	MIN	NOM	MAX
b	0.32	0.42	0.52
b1	0.40	0.50	0.60
D1	1.40	1.60	1.80
D	4.40	4.50	4.60
E	2.30	2.45	2.60
E1	3.80	4.05	4.30
e	1.30	1.50	1.70
G	2.80	3.00	3.20
A	1.40	1.50	1.60
C	0.34	0.39	0.44
L	0.80	1.00	1.20

1. All dimensions are in millimeters.

2. Dimensions do not include mold protrusions.



Marking Information:



Product: AP2310GG

Package:

GG = RoHS-compliant, halogen-free SOT-89

Date/lot code

Y = Last digit of the year

WW = Work week

S = lot code sequence

Packing:

Parts are shipped on tape and reel, 1000pcs per reel. The reel is sealed in a moisture barrier bag (MBB). Once the bag is opened, the parts should be considered moisture-sensitive, as defined in IPC/JEDEC standard, J-STD-020C, with MSL=3, and handled accordingly.